SUPPLEMENTARY INFORMATION

Fully solution-processable fabrication of multi-layered circuits on flexible substrate using laser

Seok Young Ji1,2, Wonsuk Choi2,3, Hoon-Young Kim2,3, Jin-Woo Jeon3, Sung-Hak Cho2,3 and Won Seok Chang1,2,*

1 Department of Nano Mechanics, Nanomechanical Systems Research Division, Korea Institute of Machinery and Materials, 156 Gajeongbuk-Ro, Yuseong-Gu, Daejeon 34103, Republic of Korea
2 Department of Nano-Mechatronics, Korea University of Science and Technology (UST), 217 Gajeong-Ro, Yuseong-Gu, Daejeon 34113, Republic of Korea
3 Department of Laser & Electron Beam Application, KIMM, Korea Institute of Machinery and Material, 156 Gajeongbuk-Ro, Yuseong-Gu, Daejeon 34103, Korea

* Corresponding Author: paul@kimm.re.kr; Tel.: +82-42-868-7134

Received: date; Accepted: date; Published: date
Supplementary Fig. S1. Cross-sectional SEM image of electrode lines using (a) single irradiation method and (b) double irradiation method with the surface sintering of laser power of 20 mW at various laser powers. All printed patterns were fabricated on PI substrate.
Supplementary Fig. S2. Cross-sectional SEM image of electrode lines using (a) single irradiation method and (b) double irradiation method with the surface sintering of laser power of 20 mW at various laser powers. All printed patterns were fabricated on PVP insulating layer.
Supplementary Fig. S3. Electric conductivity versus laser power on (a) PI substrate and (b) PVP insulating layer.